

DA3X108K

Silicon epitaxial planar type

For small current rectification

■ Features

- Small reverse current I_R
- Contributes to miniaturization of sets, reduction of component count.
- Eco-friendly Halogen-free package

■ Packaging

Embossed type (Thermo-compression sealing): 3000 pcs / reel (standard)

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	300	V
Maximum peak reverse voltage	V_{RM}	300	V
Output current	I_O	100	mA
Repetitive peak forward current	I_{FRM}	225	mA
Non-repetitive peak forward surge current *	I_{FSM}	500	mA
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

Note) *: 1 t = 1 s

■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 200 \text{ mA}$			1.2	V
Reverse current	I_{R1}	$V_R = 200 \text{ V}$			200	nA
	I_{R2}	$V_R = 300 \text{ V}$			1	μA
Terminal capacitance	C_t	$V_R = 0 \text{ V}, f = 1 \text{ MHz}$		3.5		pF

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

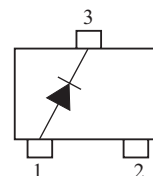
2. Absolute frequency of input and output is 3 MHz

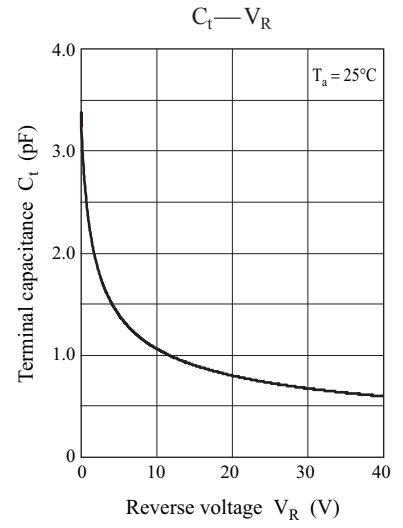
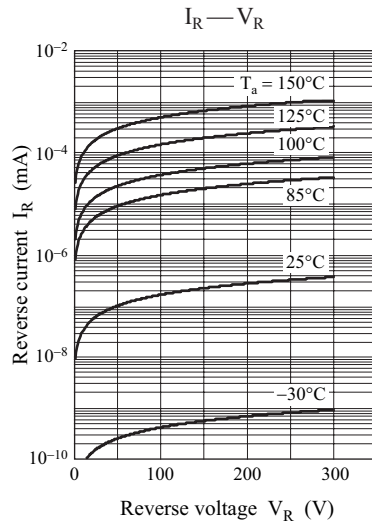
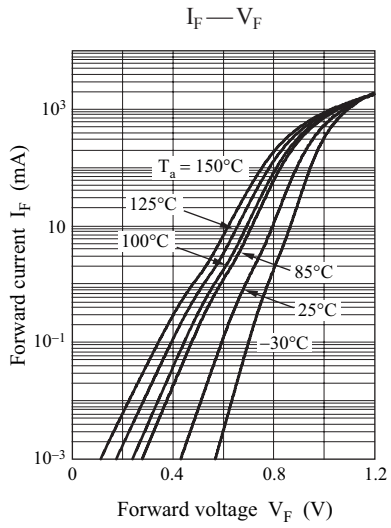
■ Package

- Code
Mini3-G3-B
- Pin Name
1: Anode
2: N.C.
3: Cathode

■ Marking Symbol: 26

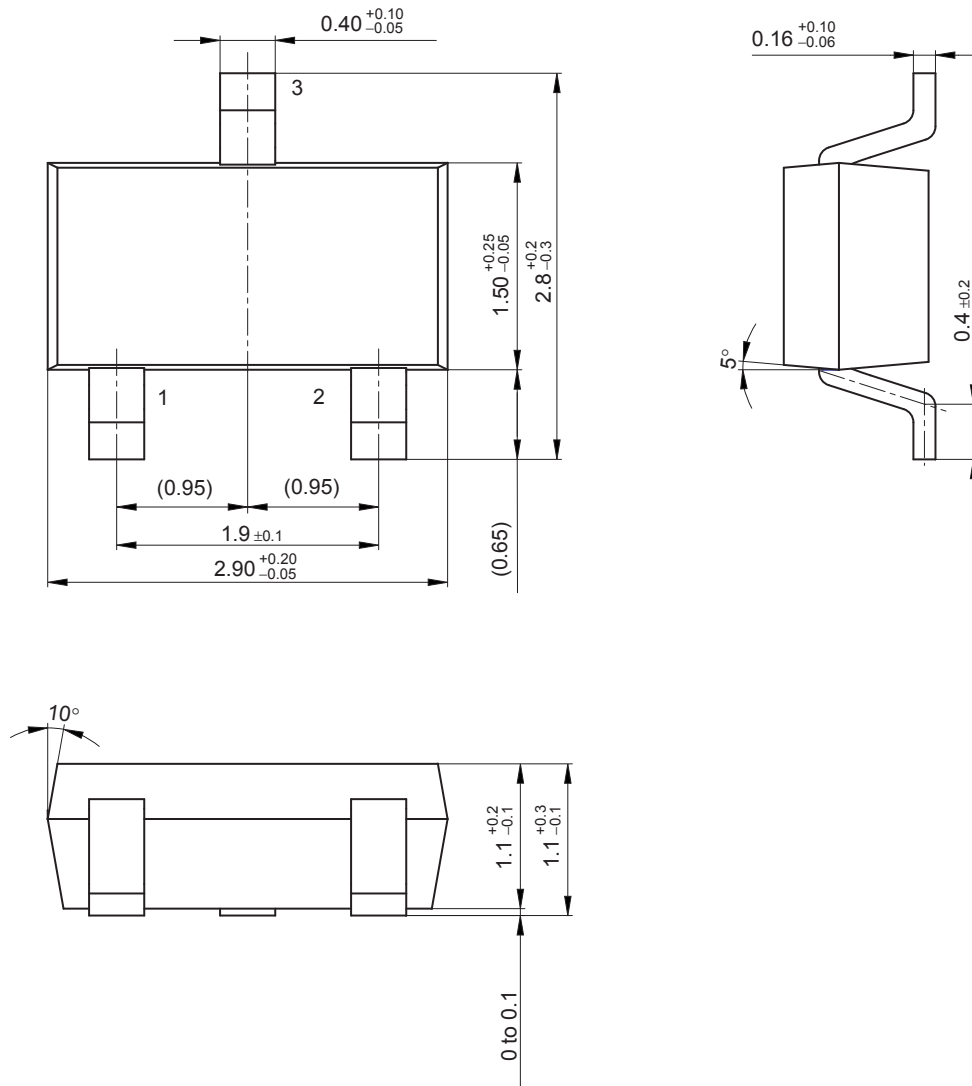
■ Internal Connection





Mini3-G3-B

Unit: mm



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